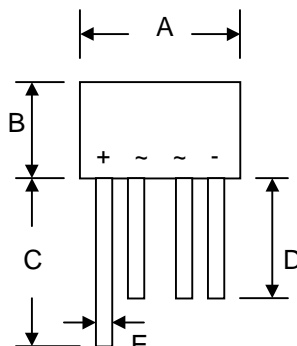


### Features

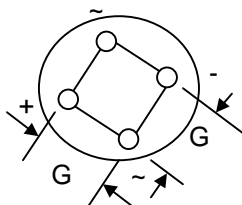
- Diffused Junction
- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability
- Ideal for Printed Circuit Boards

### Mechanical Data

- Case: Molded Plastic
- Terminals: Plated Leads Solderable per MIL-STD-202, Method 208
- Polarity: As Marked on Body
- Weight: 1.1 grams (approx.)
- Mounting Position: Any
- Marking: Type Number



WOB		
Dim	Min	Max
A	8.60	9.10
B	5.0	5.50
C	27.9	—
D	25.4	—
E	0.71	0.81
G	4.60	5.60
All Dimensions in mm		



### Maximum Ratings and Electrical Characteristics @T<sub>A</sub>=25°C unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	B40C 1500	B80C 1500	B125C 1500	B250C 1500	B380C 1500	B500C 1500	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>							
Working Peak Reverse Voltage	V <sub>RWM</sub>	100	200	300	600	900	1200	V
DC Blocking Voltage	V <sub>R</sub>							
Input Voltage Recommended	V <sub>R(RMS)</sub>	40	80	125	250	380	500	V
Average Rectified Output Current (Note 1) @T <sub>A</sub> = 50°C	I <sub>O</sub>	1.5						A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	50						A
Forward Voltage (per element) @I <sub>F</sub> = 1.5A	V <sub>FM</sub>	1.0						V
Peak Reverse Current @T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @T <sub>A</sub> = 100°C	I <sub>RM</sub>	10 500						μA
Operating Temperature Range	T <sub>j</sub>	-55 to +125						°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150						°C

Note: 1. Leads maintained at ambient temperature at a distance of 9.5mm from the case.

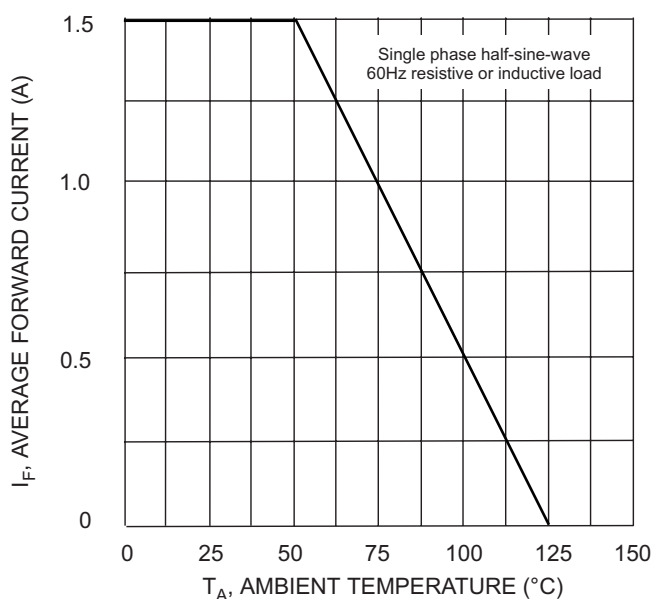


Fig. 1 Forward Current Derating Curve

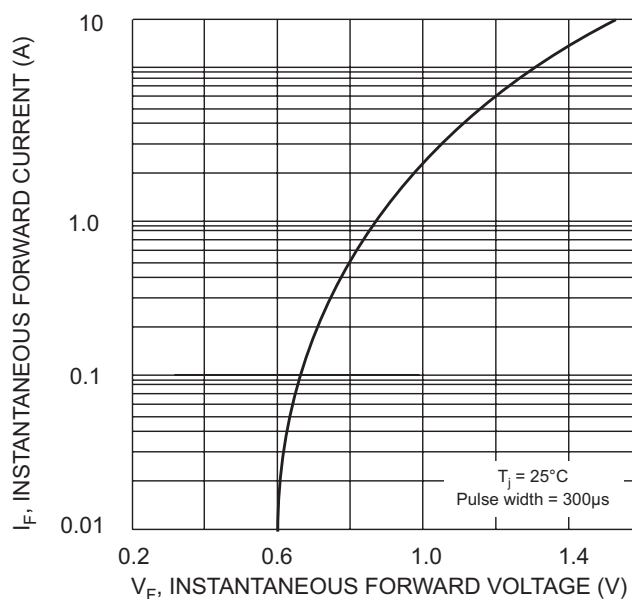


Fig. 2 Typical Forward Characteristics, per element

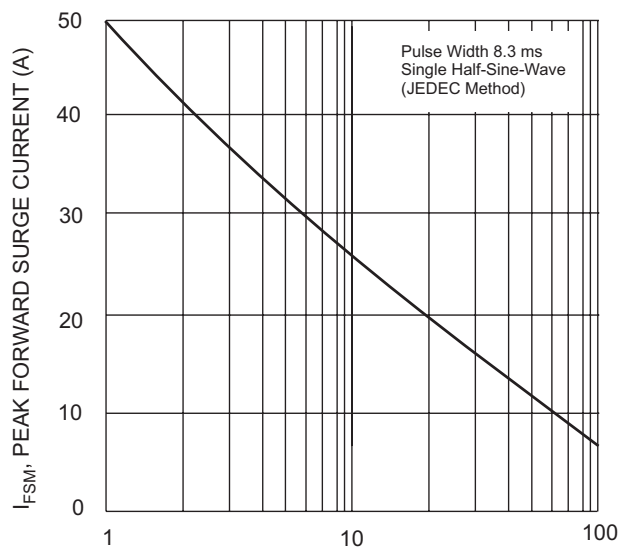


Fig. 3 Max Non-Repetitive Surge Current

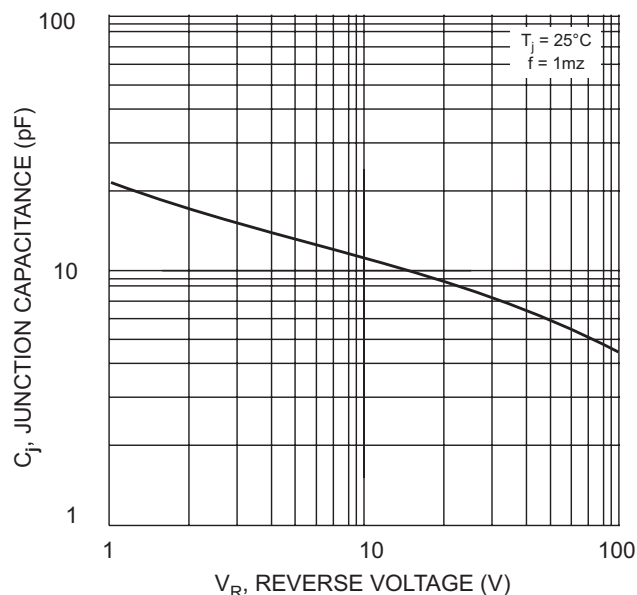


Fig. 4 Typical Junction Capacitance